

## **Materials Declaration Form**

IPC	1752		
Form Type *	Distribute	Version	2
Sectionals *	Material Info	Subsectionals *	A-D
Sectionals	Manufacturing Info	Subsectionals	* : Required Field
	Manufacturing into		. Requireu rieiu
Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-05-26
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.ht	ml	
STMicroelectronics disclaims all warra	anties, express or implied related to this docur r purpose and non-infringement. ST shall have no	ment and its contents, including but	its contents are provided on a strict 'as is' and 'as available' basis. not limited to implied warranties of completeness, truth, accuracy, for any cost, loss or damage of any kind which could arise, directly or
Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	that Supplier completes this form. Supplier ackn acknowledges that Supplier may have relied on verified such information. However, in situatio	nowledges that Company will rely on the information provided by others in co- ons where Supplier has not independ ons regarding their contributions to the	is true and correct to the best of its knowledge and belief, as of the date his certification in determining the compliance of its products. Company impleting this form, and that Supplier may not have independently ently verified information provided by others, Supplier agrees that, at a le part(s), and those certifications are at least as comprehensive as the top acreament with reserved to the identified part(s).

Product									
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date					
	1D6R*27L4AAW	А	64BA	2020-05-26					
	Amount	ST ECOPACK Grade							
	55	mg	Each	ECOPACK® 3					
Comment	COPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Intimony								

Manufacturing information									
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles							
1	260	3							
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life.augmented					
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		moradginomod					
	-								
Package Designator	Package Size	Nbr of instances	Shape						
DSO	5 x 4.4	14	Gull wing						
Comment 6R TSSOP 14 BODY 4.4 PITCH 0.65; MDF is valid for TS27L4IPT									

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Directive 2015/863-March 2015							
	Query	Response					
1 - Product(s) meets EU RoHS requirement w	vithout any exemptions	true					
2 - Product(s) meets EU RoHS requirements	- Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply) false						
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) false							
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions false							
Exemption Id. Description							
QueryList : ELV directive : 2000/53/EC a	mended 2020/363_March 2020						
	Query Response						
1 - Product(s) meets EU ELV requirements w	ithout any exemptions	true					
2 - Product(s) meets EU RoHS requirements	by application of the selected exemption(s)	false					

QueryList : California Prop65 list, dated 3rd January 2020								
Query	Response							
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen false								
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consu	true							
Substance	ppm in product							
Nickel	7059							

Description

Exemption Id.

QueryList : REACH-16th January 2020								
	Response							
1 - Product(s) does not contain REACH Subst	true							
CategoryLevel_Name	ategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application							
,	0							
2 - Product(s) does not contain REACH Su REACH	ubstances Of Very High Concern in any Embedded	article nor Homogeneous Material abo	ve the limits per the definition within	true				
CategoryLevel Name CategoryLevel Threshold		Amount in Embedded Article / Application - Article / Homogene Homogeneous Material (mg) Material		us ppm in Article /Homogeneous Material				
,								

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update								
	Response							
The Product does contain at least one o	f the substances listed in Chemical Control Act			false				
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose				

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document			Mfr Item Name	1	D6R*27L4AAW			5000001.0	999999.0			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.299	mg	supplier	die	Silicon(Si)	7440-21-3		2.242	mg	975207	40897
				supplier	metallisation	Aluminium(AI)	7429-90-5		0.009	mg	3915	164
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.006	mg	2610	109
				supplier	passivation	Silicon oxide	7631-86-9		0.042	mg	18269	766
Leadframe	M-004 Copper and its alloys	20.986	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		20.021	mg	954017	365213
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.387	mg	18441	7059
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.471	mg	22444	8592
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.028	mg	1334	511
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.025	mg	1191	456
				supplier	alloy & coating	Palladium(Pd)	7440-05-3		0.047	mg	2240	857
				supplier	alloy & coating	Gold(Au)	7440-57-5		0.007	mg	334	128
Die attach	M-015 Other organic materials	0.140	mg	supplier	glue	Silver(Ag)	7440-22-4		0.123	mg	878571	2244
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.007	mg	50000	128
				supplier	glue	Isobornyl acrylate	5888-33-5		0.007	mg	50000	128
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.003	mg	21429	55
Bonding wires	M-004 Copper and its alloys	0.083	mg	supplier	wire	Copper(Cu)	7440-50-8		0.083	mg	1000000	1514
Encapsulation	M-015 Other organic materials	31.312	mg	supplier	mold compound	Silica vitreous	60676-86-0		22.419	mg	715987	408957
				supplier	mold compound	Silicon oxide	7631-86-9		4.697	mg	150006	85680
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		2.348	mg	74987	42831
				supplier	mold compound	Phenol resin	26834-02-6		1.566	mg	50013	28566
				supplier	mold compound	Carbon black	1333-86-4		0.157	mg	5014	2864
				supplier	mold compound	Bismuth compound	7440-69-9		0.125	mg	3992	2280